



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: AAAF3529SEEZGKBKS

Hyper Red
Green
Blue

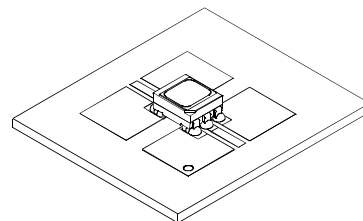
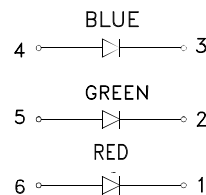
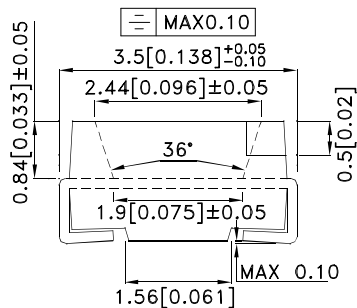
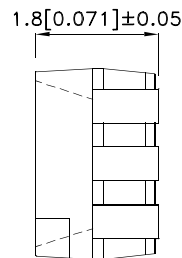
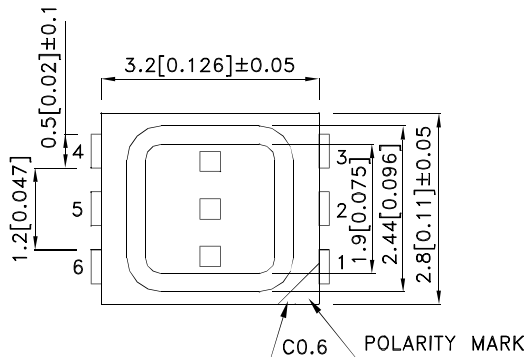
Features

- Outstanding material efficiency.
- Low power consumption.
- Can produce any color in visible spectrum, including white light.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- RoHS compliant.

Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- The Blue source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

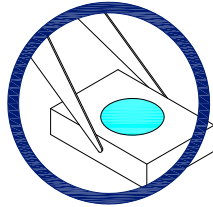


Handling Precautions

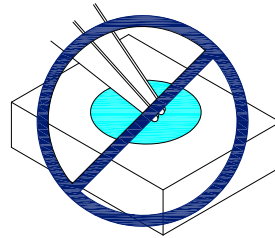
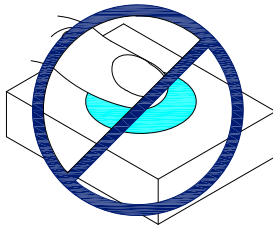
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly Orangeuces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

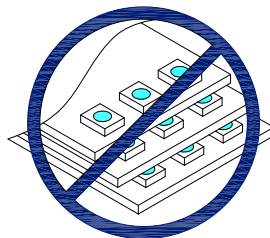
1. Handle the component along the side surfaces by using forceps or appropriate tools.



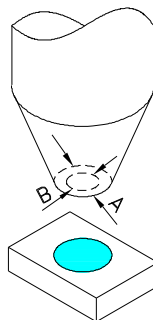
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AAAF3529SEEZGKQBKS	Hyper Red (AlGaInP)	Water Clear	80	180	120°
	Green (InGaN)		400	580	
	Blue (InGaN)		80	130	

Notes:

1. $\theta 1 / 2$ is the angle from optical centerline where the luminous intensity is 1 / 2 of the optical peak value.
2. Luminous intensity / luminous Flux: + / -15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Hyper Red Green Blue	630 515 460		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Hyper Red Green Blue	621 525 465		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red Green Blue	20 30 25		nm	I _F =20mA
C	Capacitance	Hyper Red Green Blue	25 45 100		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Hyper Red Green Blue	2 3.3 3.3	2.5 4.1 4	V	I _F =20mA
I _R	Reverse Current	Hyper Red Green Blue		10 50 50	uA	V _R =5V

Notes:

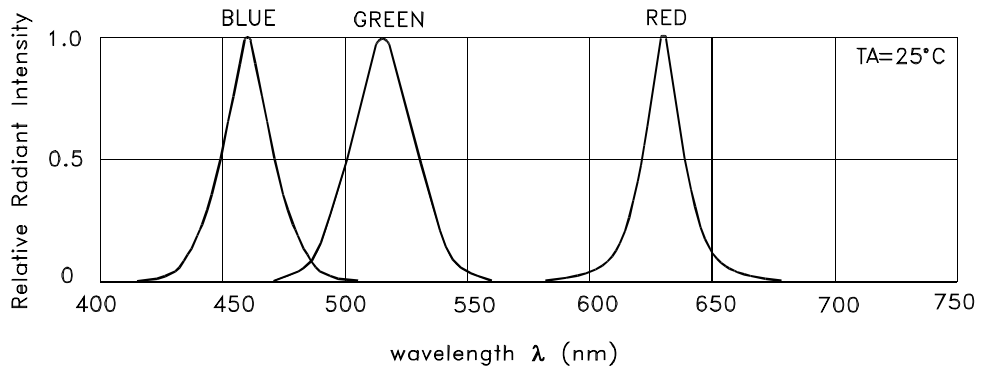
1. Wavelength: + / -1nm.
2. Forward Voltage: + / -0.1V.
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Blue	Units
Power dissipation	125	123	120	mW
DC Forward Current	50	30	30	mA
Peak Forward Current [1]	195	150	150	mA
Reverse Voltage	5			V
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

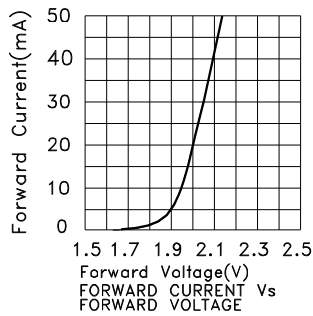
Notes:

1. 1 / 10 Duty Cycle, 0.1ms Pulse Width.

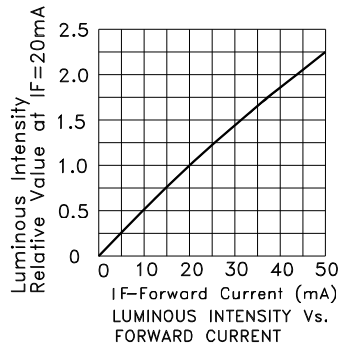


RELATIVE INTENSITY Vs. WAVELENGTH

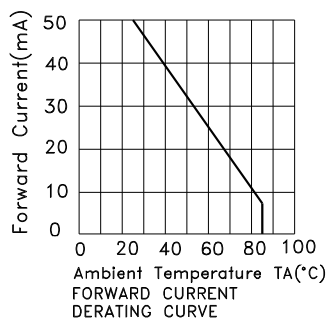
AAAF3529SEEZGKBKS Hyper Red



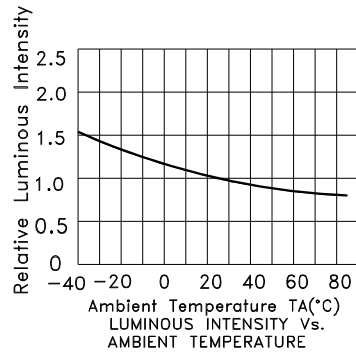
FORWARD CURRENT Vs. FORWARD VOLTAGE



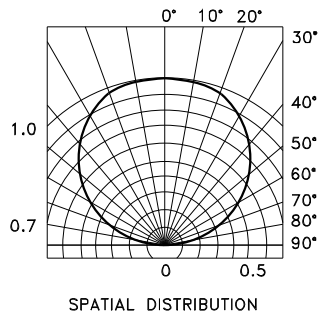
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE

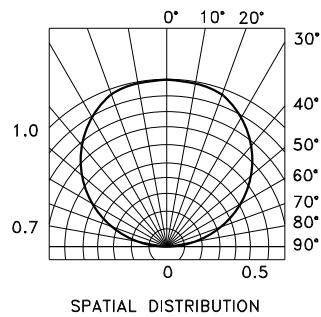
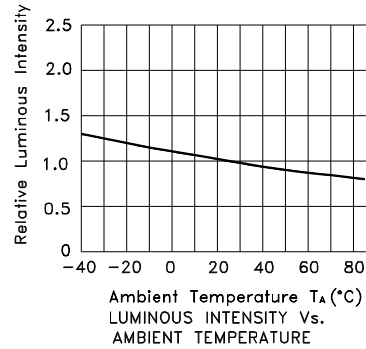
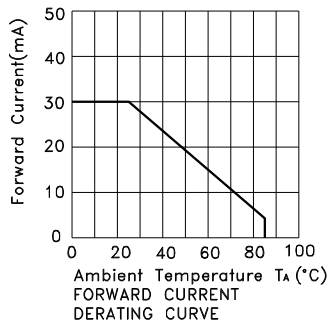
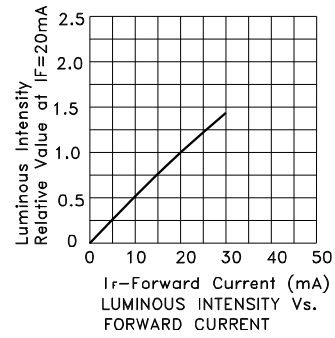
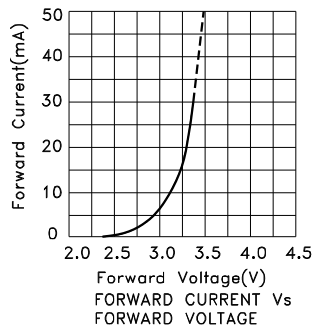


LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

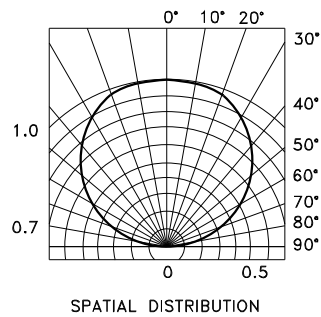
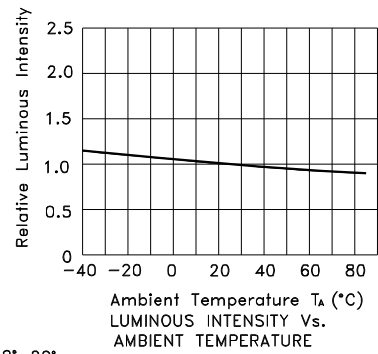
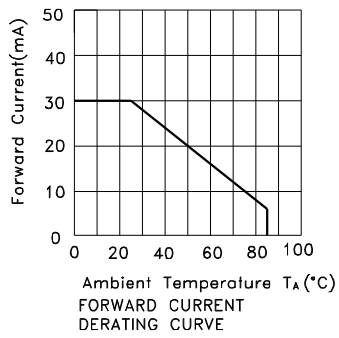
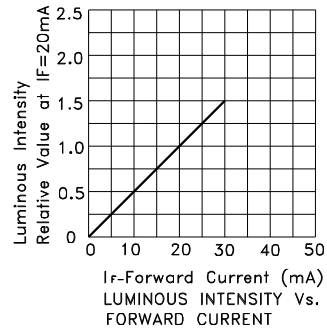
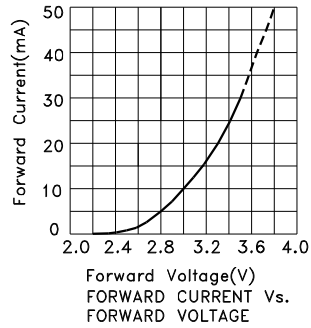


SPATIAL DISTRIBUTION

Green



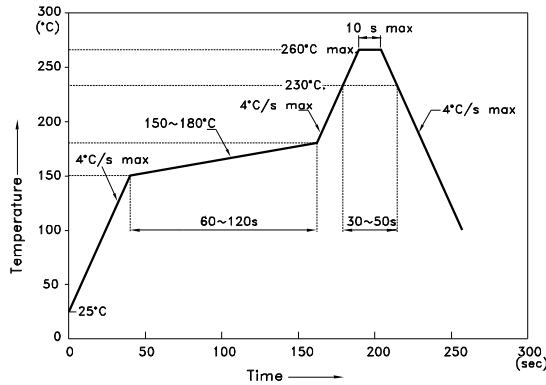
Blue



AAAF3529SEEZGKBKS

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

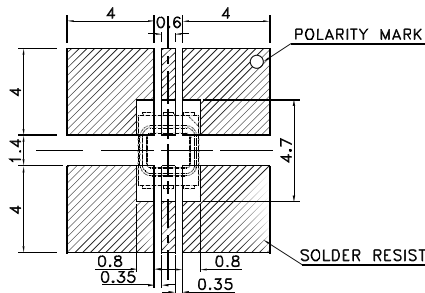
Reflow Soldering Profile For Lead-free SMT Process.



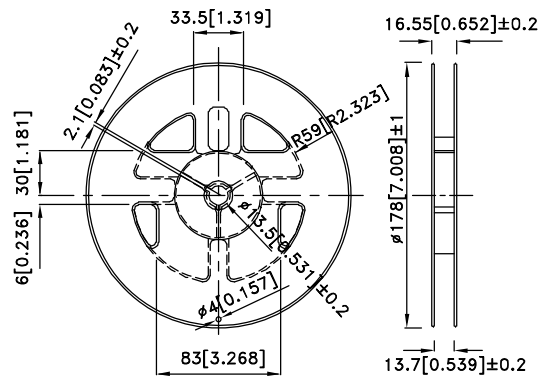
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

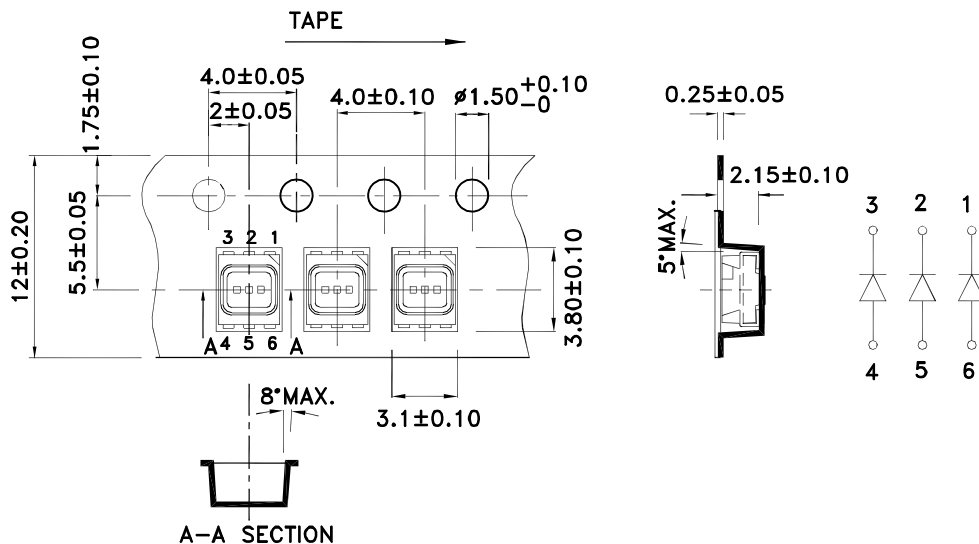
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

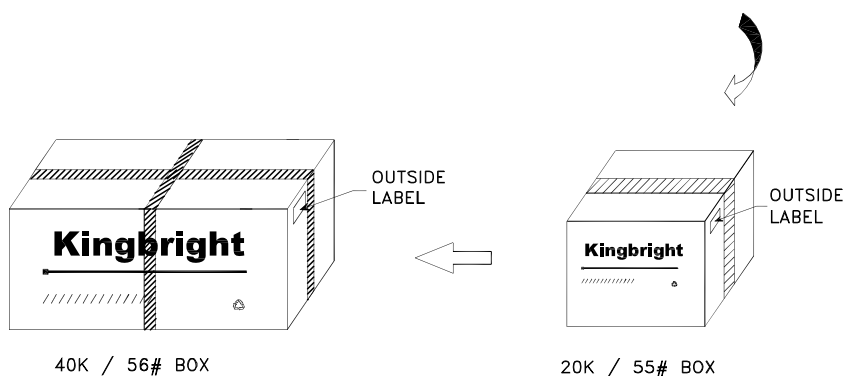
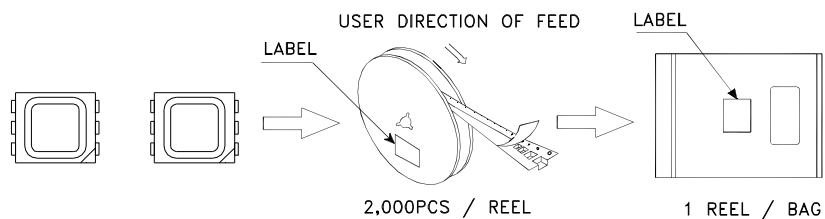



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

AAAF3529SEEZGKBKS



Kingbright	
P/NO: AAAF3529xxx	
QTY: 2,000 pcs	Q.C. Q C xx xx xxxx PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	

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